

## EAST Search History

| Ref # | Hits | Search Query  | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|------|---|---|------------------|---------|------------------|
| L1    | 882  | "thermosetting resin" same (polyimide or silicone) and infrared and (ultraviolet or uv)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/03/14 13:54 |
| L3    | 355  | "circuit board" with cpu and "257"/\$.ccls.   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/03/14 13:55 |
| S1    | 1477 | (257/706).CCLS.   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2006/03/13 10:27 |
| S2    | 13   | ("5002818"   "5396403"   "5471366"   "5710733"   "5866943"   "5900312"   "6011697"   "6060150"   "6212074"   "6275381"   "6285078"   "6348679"   "6496373").PN. OR ("6707671"). URPN.   | US-PGPUB;<br>USPAT;<br>USOCR                                      | OR               | ON      | 2006/03/13 13:34 |
| S3    | 21   | ("4985186"   "5155661"   "5184211"   "5285108"   "5371654"   "5426405"   "5450283"   "5530291"   "5621615"   "5672548"   "5726079"   "5744863"   "5757621"   "5785799"   "5888849"   "5947750"   "5990552"   "6191480"   "6212074"   "6340894").PN. OR ("6590278"). URPN. | US-PGPUB;<br>USPAT;<br>USOCR                                      | OR               | ON      | 2006/03/13 13:37 |
| S4    | 56   | ("3586102"   "4563725"   "4833567"   "5126919"   "5168919"   "5296739"   "5323292"   "5430611"   "5508884"   "5713690"   "5754401"   "5829512"   "5831831"   "5863814"   "5880524"   "5880930"   "5932925"   "5945217").PN. OR ("6212074"). URPN.                         | US-PGPUB;<br>USPAT;<br>USOCR                                      | OR               | ON      | 2006/03/13 13:44 |

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|     |       |  |   |    |     |                  |
|-----|-------|--|---|----|-----|------------------|
| S5  | 2     | ("20020179289").PN.  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2006/03/13 15:33 |
| S6  | 26416 | "heat pipe"  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2006/03/13 15:34 |
| S7  | 505   | "heat pipe" and "semiconductor chip"   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2006/03/13 16:01 |
| S8  | 928   | (resin with thermosetting) with "protective layer"                                   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2006/03/13 16:07 |
| S9  | 697   | (resin with thermosetting) with peel\$3  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2006/03/13 16:24 |
| S10 | 416   | (resin with thermosetting) with release adj (paper or layer or film)                 | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2006/03/13 17:22 |
| S11 | 23    | "Nakata, Yasukazu".in.   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2006/03/13 17:22 |
| S12 | 5     | ("5864178"   "6100597"   "6225704"   "6437450"   "6589802").PN. OR ("6927099").URPN. | US-PGPUB;<br>USPAT;<br>USOCR                                      | OR | ON  | 2006/03/14 13:23 |